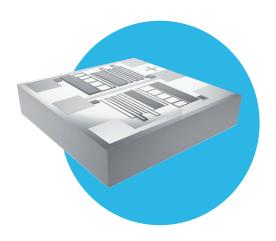
### Resistors

# Wire Bondable **Ceramic Resistors**

#### **WBA Series**

- High resistor density
- Lower stray capacitance
- Proven TaNFilm® on ceramic technology







All parts are Pb-free and comply with EU Directive 2011/65/EU amended by (EU) 2015/863 (RoHS3)

IRC's WBA series wire bondable ceramic resistors are ideally suited for your most demanding hybrid application. IRC's TaNFilm® tantalum nitride thin film technology has years of proven stability, reliability and moisture performance.

IRC's WBA series of ceramic chip resistors offer a wide range of tolerances and temperature coefficients to fit a variety of hybrid circuit applications. Custom resistance values, sizes and schematics are also available on request to the factory.

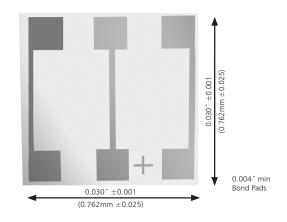
For high performance wire bondable ceramic resistors for hybrid circuit application, specify IRC WBA series resistors.

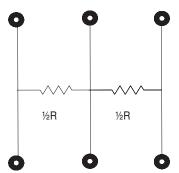
#### **Electrical Data**

| Absolute Tolerance                                    | to ±0.1%                         |  |  |  |  |
|---|----------------------------------|--|--|--|--|
| Ratio Tolerance                                       | to ±0.05%                        |  |  |  |  |
| Absolute TCR  | to ±25ppm/°C                     |  |  |  |  |
| Tracking TCR  | to ±2ppm/°C                      |  |  |  |  |
| Package Power Rating (@ 70°C)                         | 250mW                            |  |  |  |  |
| Rated Operating Voltage (not to exceed $\sqrt{PxR}$ ) | 100V                             |  |  |  |  |
| Operating Temperature                                 | -55°C to +150°C                  |  |  |  |  |
| Noise   | <-30dB                           |  |  |  |  |
| Substrate Material                                    | 99.6% Alumina                    |  |  |  |  |
| Substrate Thickness                                   | 0.015″ ±0.002<br>(0.381mm ±0.05) |  |  |  |  |
| Bond Pad Metallization                                | Gold: 30KÅ minimum               |  |  |  |  |
| Backside  | Ceramic (gold available)         |  |  |  |  |

## Physical Data

T0303 - Tapped network





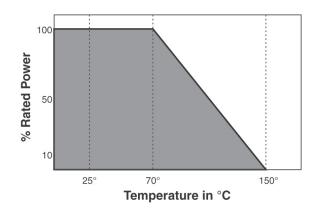
TT Electronics reserves the right to make changes in product specification without notice or liability. All information is subject to TT Electronics' own data and is considered accurate at time of going to print. BI Technologies IRC Welwyn



# Manufacturing Capabilities Data

| Resistance Range | Available Absolute<br>Tolerances | Available Ratio<br>Tolerances | Best Absolute TCR | Tracking TCR |
|------------------|----------------------------------|-------------------------------|-------------------|--------------|
| 10Ω-20Ω          | GJK                              | FGJ                           | ±100ppm/°C        | ±5ppm/°C     |
| 21Ω–50Ω          | FGJK                             | FGJ                           | ±100ppm/°C        | ±5ppm/°C     |
| 51Ω-100Ω         | CDFG                             | CDFG                          | ±100ppm/°C        | ±5ppm/°C     |
| 101Ω–200Ω        | CDFG                             | CDFG                          | ±50ppm/°C         | ±5ppm/°C     |
| 201Ω–500Ω        | BCDFG                            | BCDFG                         | ±50ppm/°C         | ±5ppm/°C     |
| 501Ω-999Ω        | BCDFG                            | BCDFG                         | ±25ppm/°C         | ±5ppm/°C     |
| 1.0ΚΩ-20ΚΩ       | BCDFG                            | ABCDFG                        | ±25ppm/°C         | ±2ppm/°C     |

# **Power Derating Data**



# TCR/Inspection Code Table

| Absolute TCR | Commercial<br>Code | MIL Inspection<br>Code |
|--------------|--------------------|------------------------|
| ±300ppm/°C   | 00                 | 04                     |
| ±100ppm/°C   | 01                 | 05                     |
| ±50ppm/°C    | 02                 | 06                     |
| ±25ppm/°C    | 03                 | 07                     |

\*Notes: Product supplied to Class H of MIL-PRF 38534 include 100% visual inspection

#### Wire Bondable **Ceramic Resistors**





### **Environmental Data**

| Test                         | Method  | Max ∆R | Typical ∆R |
|------------------------------|---|--------|------------|
| Thermal Shock                | MIL-STD-202 Method 107<br>Test condition F      | ±0.1%  | ±0.02%     |
| High Temperature Exposure    | MIL-STD-883<br>Method 1008<br>150°C, 1000 hours | ±0.1%  | ±0.05%     |
| Low Temperature Storage      | -55°C, 1000 hours                               | ±0.03% | ±0.01%     |
| Life                         | MIL-STD-202<br>Method 108<br>70°C, 1000 hours   | ±0.5%  | ±0.01%     |
| Life at Elevated Temperature | MIL-STD-202<br>Method 108<br>125°C, 1000 hours  | ±0.5%  | ±0.05%     |

# Ordering Data

| Prefix · · · · WB   | Α -     | T0303       | (   | à     | С       | - 01    | -     | 1002      | -   | F     | В |
|---|---------|-------------|-----|-------|---------|---------|-------|-----------|-----|-------|---|
| Style · · · · · · · · · · · · · · · · · · ·   |         |             |     |       |         |         |       |           |     |       |   |
| <b>Bonding pads</b> · · · · · · · · · · · · · · · · · · ·   |         |             |     |       |         |         |       |           |     |       |   |
| Backside  | • • •   | •••••       | ••• | • • • | :       |         |       |           |     |       |   |
| Absolute TCR Code · · · · · · · · · · · · · · · · · · ·   | •••     | • • • • • • | ••• | • • • | •••     |         |       | •         |     |       |   |
| Total Resistance = R · · · · · · · · · · · · · · · · · ·  | 1 = 50  | .1Ω         |     |       |         |         |       |           |     |       |   |
| Absolute Tolerance Code K = $\pm 10\%$ ; J = $\pm 5\%$ ; G = $\pm 2\%$ ; F = $\pm 1\%$ ; D = $\pm 0.5\%$ ; C = $\pm 0.25\%$ ; B = $\pm 0.1\%$ | • • • • | • • • • •   | ••• | • •   | • • • • | • • • • | • • • | • • • • • | ••  | •     |   |
| Ratio Tolerance Code  | • • • • | • • • • •   | ••• | • • • | • • • • | •••     |       | • • • • • | • • | • • • |   |

**Packaging**Standard packaging is 2" x 2" chip tray. For additional information or to discuss your specific requirements, please contact our Applications Team using the contact details below.